I. Introduction

Goal: Development of nanoparticle based-inks compatible with Super Ink Jet Printer for extreme environments

- Printed electronics are important for several reasons.
- Enables the fabrication of flexible and lightweight electronic devices • Offers cost-effective manufacturing processes
- Allows for large-scale production and potential integration into various industries such as consumer electronics, energy, and healthcare.
- Wearable biosensors and Internet of Things (IoT) shown great potential in healthcare and environmental monitoring offering suitable, low-cost, portable instruments for detecting infections, proteins, and other analytes quickly.¹

SIJ Advantages ²					SIJ Disadva		
• Noncontact patterning technique thus safe to use for multilayer processes				• Prone to nozzle clogging			
• Variety of materials processable				• Glass tips are easily broken			
• Does not require vacuum				• Resolution limited by nozz			
• Highly reproducible				• Unable to process material			
• No substrate modification required to achieve high resolution				• High initial setup cost			
Printer	Spatial Resolution	3D Printing (Y/N)	Particle S	bize	Viscosity (cP)	Solver	

11P 3,4,5	18 um	No	50-200 nm	<16	MEK
	10 μΠ	110	<u> </u>	<10	Polar
					Solven
SIJ ^{2,6,7,8}					(water
	<u><</u> 50 nm	Yes	140 - 1517nm	1-1000	ethano
					Ethyler
			<200 nm		glycol, w
A.JP ^{9,10,}			preferred (300-		Polyimi
11	<20 µm	Yes	500 nm max)	1-1000	Polyureth
					Polar
PJP ^{12,13,}					Solven
14	~10 µm->1µm	Yes	40-60 µm	1-5	(PVAI
Resolution	Piezoelectric actuator Ink Nozzle Droplet	Electrodes	Sintering J. Mansi, et al, Nanoscale., 2023 R. Gandhiraman, et al., ACS Nano 2018 R. Gandhiraman, et al., APL 2016 J. Manzi, P. Sweeney, Researchers Earn NASA Grant to Explore Pla Space Manufacturing,, 2019	sma-Jet Printing for In-	
	Substrate Carrier Gas In (q.) Ultrasonic Atomization o Nanoparticle Ink	Atomized In Carried to Printh Sheath Gas In (q)	Image Courtesy of Fujifilm, 2023	ntering St Nanoeng., in press 2023 Fech, 2020 018	
High	(c) Syringe pump Microscope camera	Capillary	High voltage supply E. Jabari et T. Pandhi et N. Mkhize, Printing: Int Consideration Starge	I. 2D Materials, 2019 ., RSC Advances, 2020 Electrohydrodynamic Jet roductory Concepts and ons, 2021	
	Center for Advanced Energy Studies	Idaho National L	aboratory	Idaho	<u>State</u>

Ink formulation for SIJ in Extreme Environments

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orge Number $=\frac{\mu_g}{\sqrt{\sigma\rho dn}}$		Reynold's Number $Re = \frac{q_g \rho_g}{\pi r_n^2 \mu_g} d_n$	
atio	Total G	as Flow	Impinging Jet Ve

III. Results/Discussion



Figure #2: (A-B) TEM images of synthesized Au nanoparticles (A) scalebar 20 nm; (B) 10 nm. (C) DLS of SIJ Ag ink and synthesized Au nanoparticles. Au nanoparticles have a much smaller hydrodynamic size than commercially purchased SIJ Ag.





Figure #4: Thermogravimetric analysis and differential scanning calorimetry of nanoparticle inks. Au ink has little weight loss over a wide temperature range while silver shows ~30% weight loss due to polymer content-indicating minimum sintering temperature of 350° C

IV. Conclusion/ Future Work

A gold ink was synthesized that meets the technical requirements of SIJ printer, which was verified through TEM, DSC/TGA, DLS and contact angle measurements. Based on the observed characteristics it is anticipated that the as-synthesized gold ink can be printed with the SIJ printer.

Future Work:

SIJ.

- Verify Super Ink Jet printer compatibility
- Determine achievable resolution for the gold ink.
- Verify print quality.

V. Acknowledgements and References

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- References: [1] D.Verma, Biosensors and Bioelectronics: X, 2022
- [2]N. Mkhize, Small Science, 2021 [3] T. da Costa, Micro and Nano Systems Letters, 2020
- [4] R. Bernasconi, Advanced Engineering Material, 2021
- [5] J. Mancuso, Ecolink, 2021 [6]Y. Huang, Journal of Manufacturing Process, 2020
- [7] L. Guo, Micromachines (Basel), 2018



Figure #3: Optical tensiometer measurements of silver and gold ink. Top Panel: Pendant drop test for surface tension of (A) Ag ink for surface tension (B) Au ink for surface tension. Bottom panel: Contact angle measurement on glass slide (C) Ag ink (D) Au ink.

• Print strain gauges and evaluate performance in extreme environments • Use a similar process to develop additional inks (e.g. Pt) to expand the library of available inks for

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> [8] L. Liashenko, Nature Communications, 2020 [9] M. Zeng, Nature, 2023

- [10] H. Kondo, Aerosol Jet Printing, 2021
- [11] OPTOMEC, Aerosol Jet Materials, 2020 [12] Y. Huang, Int. J. Extrem. Manuf, 2021
- [13] J. Schafer, Plasma Process Polym, 2019 [14] J. Mansi, et al, Nanoscale, 2023
- [15]T. Varghese, et. Al, ACS Materials Au, submitted